



**PF06N03 V0 Preliminary**  
**Product Specification**

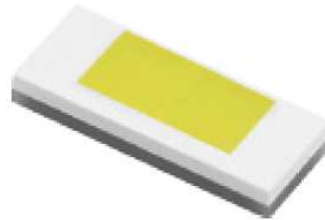
## Approval Sheet

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RoHS

<b>Product</b>	2052 White LED
<b>Part Number</b>	PF06N03
<b>Issue Date</b>	2017/9/26



### ■ Feature

- ✓ White SMD LED (L x W x H) of 2.0 x 5.2 x 0.75 mm
- ✓ Dice Technology : InGaN
- ✓ Qualified according to JEDEC moisture sensitivity Level 1
- ✓ Environmental friendly ; RoHS compliance
- ✓ Packing : 100/500/1000 pcs/reel

### ■ Applications

- ✓ DRL
- ✓ Fog light
- ✓ Head lamp

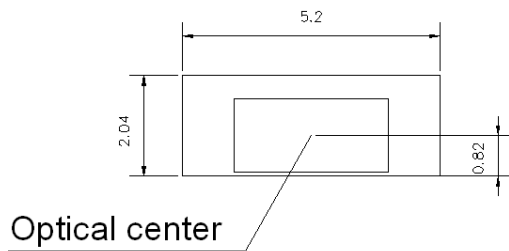
## Outline Dimension

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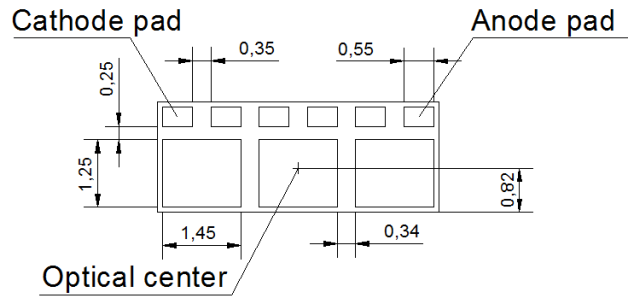
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### ■ PKG Size:

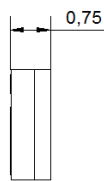
2.0 mm \* 5.2 mm \* 0.75mm (H)



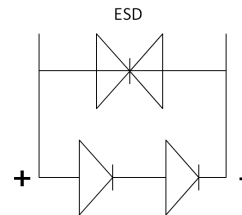
Top view



Bottom view

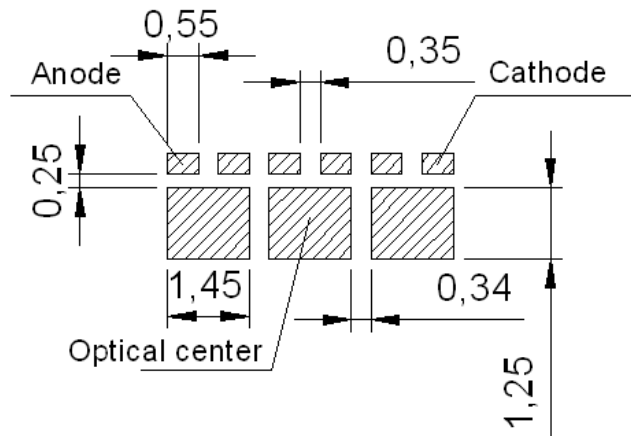


Side view



Equivalent Circuit

### ■ Recommend Soldering Pad Layout



Unit: mm, Tolerance:  $\pm 0.10$ mm

Performance

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■ **Electro-Optical Characteristics (Ta=25°C)**

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage <sup>(1)</sup>	V <sub>F</sub>	I <sub>F</sub> = 1200 mA	6.0	6.4	6.9	V
Luminous Flux	Φ <sub>V</sub>		750	800	1000	Lm
View Angle	θ		110	120	130	deg
Electrical Thermal Resistance	R <sub>th, elec</sub>		--	2.3	--	°C/W

- (1) The Forward Voltage tolerance is ±0.05V
- (2) The luminous flux tolerance is ±8%
- (3) Thermal resistance is calculated from junction to solder
- (4) Electric and optical data is tested at 50 ms pulse condition
- (5) The color coordinates measurement tolerance is ±0.005

■ **Absolute Maximum Ratings**

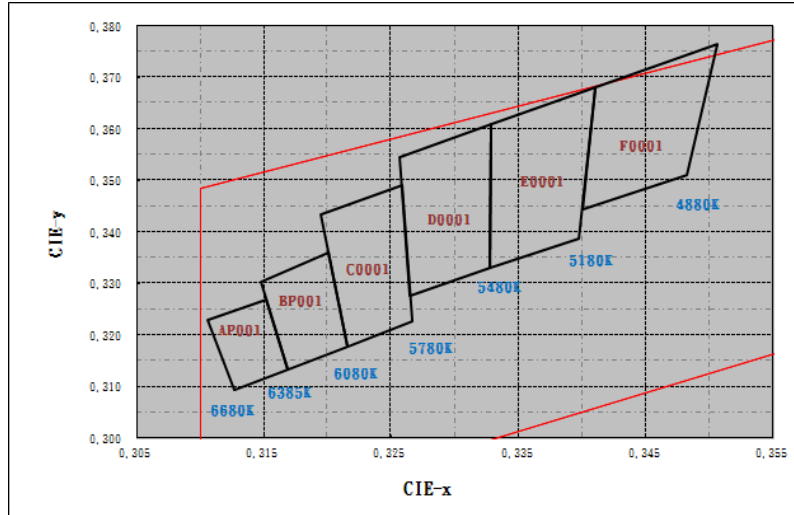
Parameter	Symbol	value	Unit
DC Forward Current <sup>(1)</sup>	I <sub>F</sub>	1500	mA
Power Dissipation	P <sub>D</sub>	9.6	W
Pulse Forward Current <sup>(2)</sup>	I <sub>FP</sub>	2000	mA
Storage Temperature	T <sub>stg</sub>	-40 ~ +125	°C
Operating Temperature	T <sub>opr</sub>	-40 ~ +125	°C
Junction Temperature	T <sub>J</sub>	150	°C
Assembly Temperature	T <sub>sld</sub>	260 (max. 30sec)	°C

- (1) Proper current rating must be observed to maintain junction temperature below maximum at all time
- (2) IFP shall be applied under condition as max duration time 400ms and 1/10 duty cycle.

**Binning**

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**Chromaticity Coordinates**



**Bin code definition**

V <sub>F</sub> Rank	Luminous Flux Rank	CIE Rank
A	U3	BP001

V <sub>F</sub> Rank	Condition	Min.	Max.
A	I <sub>F</sub> = 1200 mA Ta = 25°C	6.0	6.3
B		6.3	6.6
C		6.6	6.9

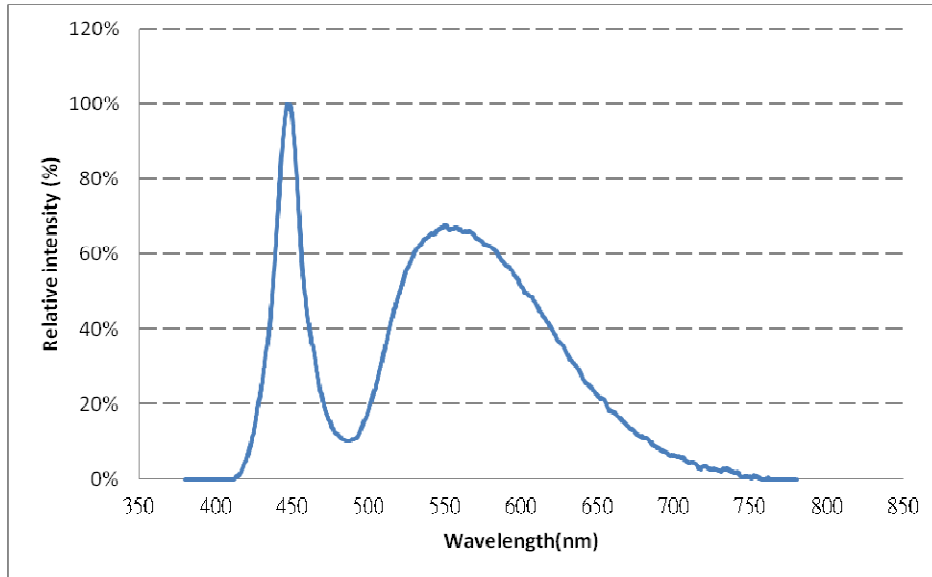
Luminous Flux Rank	Condition	Min.	Max.
U2	I <sub>F</sub> = 1200 mA Ta = 25°C	750	800
U3		800	900
U4		900	1000

■ **CIE Rank**

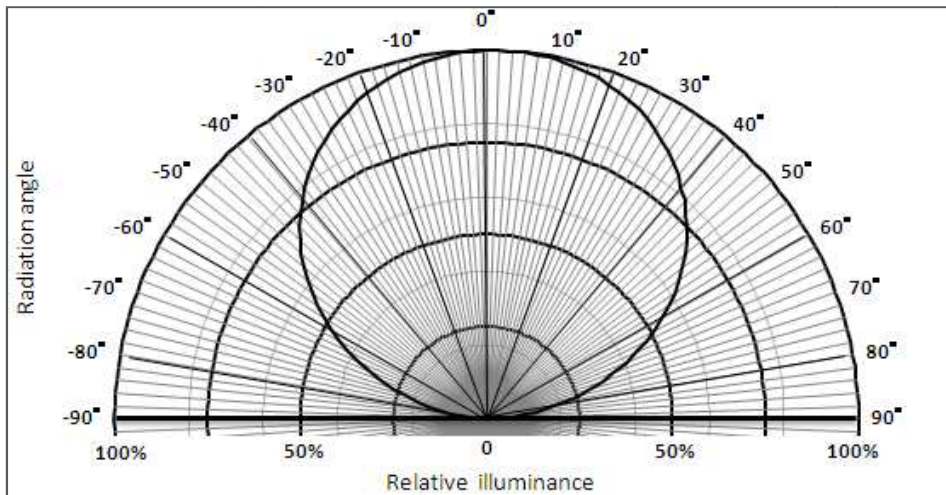
<b>CCT</b>	<b>CIE Rank</b>	<b>CIE X</b>	<b>CIE Y</b>
<b>6385 ~ 6680</b>	<b>AP001</b>	0.3106	0.323
		0.3152	0.3269
		0.3169	0.3133
		0.3127	0.3093
<b>6080 ~ 6385</b>	<b>BP001</b>	0.3148	0.3303
		0.3201	0.336
		0.3216	0.3178
		0.3169	0.3133
<b>5780 ~ 6080</b>	<b>C0001</b>	0.3195	0.3433
		0.3259	0.3491
		0.3267	0.3228
		0.3216	0.3178
<b>5480 ~ 5780</b>	<b>D0001</b>	0.3257	0.3546
		0.3328	0.3608
		0.3327	0.3331
		0.3265	0.3276
<b>5180 ~ 5480</b>	<b>E0001</b>	0.3328	0.3608
		0.3410	0.3681
		0.3397	0.3387
		0.3327	0.3331
<b>4880 ~ 5180</b>	<b>F0001</b>	0.3410	0.3681
		0.3506	0.3765
		0.3482	0.3510
		0.3400	0.3443

(1) Color bins are tested at IF = 1200mA 50ms pulse operation condition

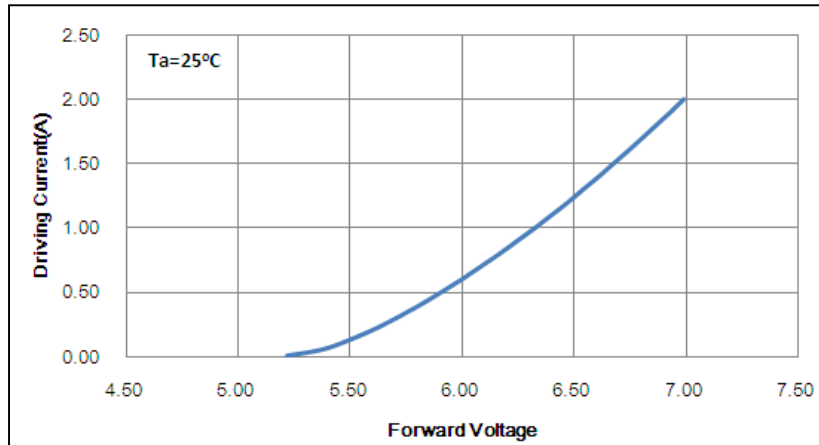
## ■ Spectrum



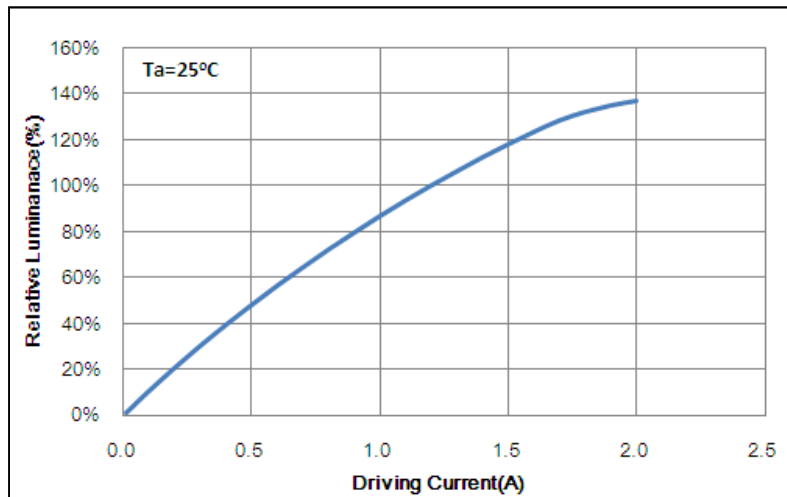
## ■ Radiation Pattern



### ■ Forward Voltage vs. Forward Current

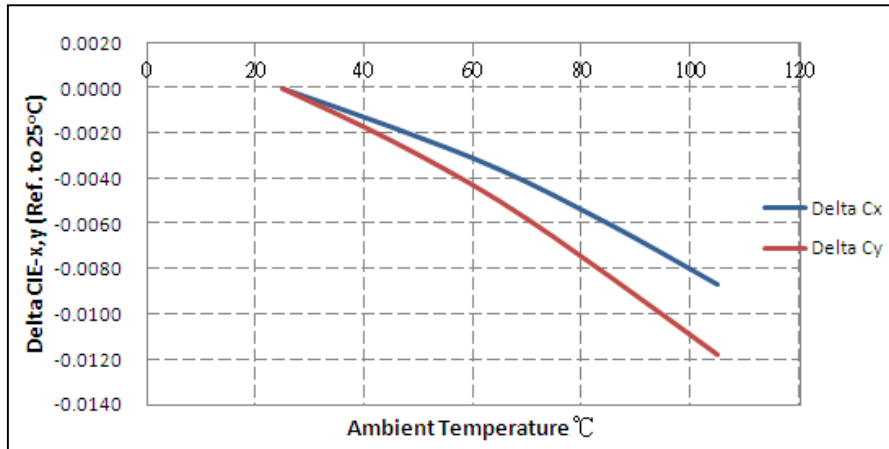


### ■ Forward Current vs. Relative Luminosity

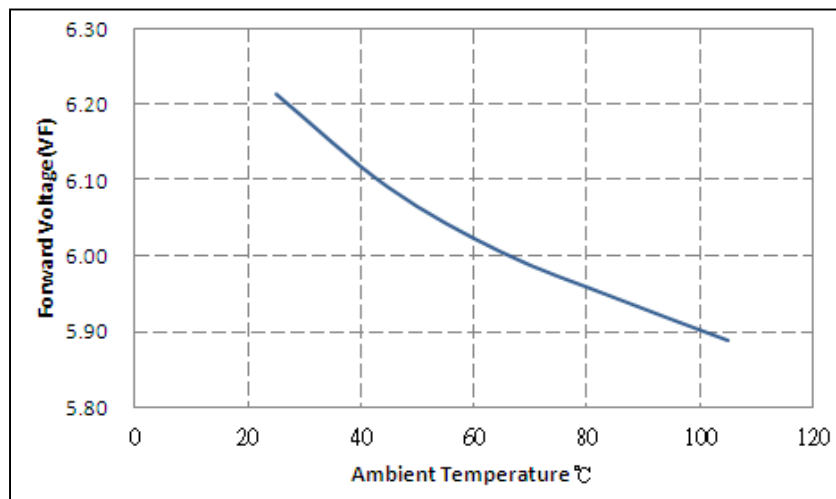




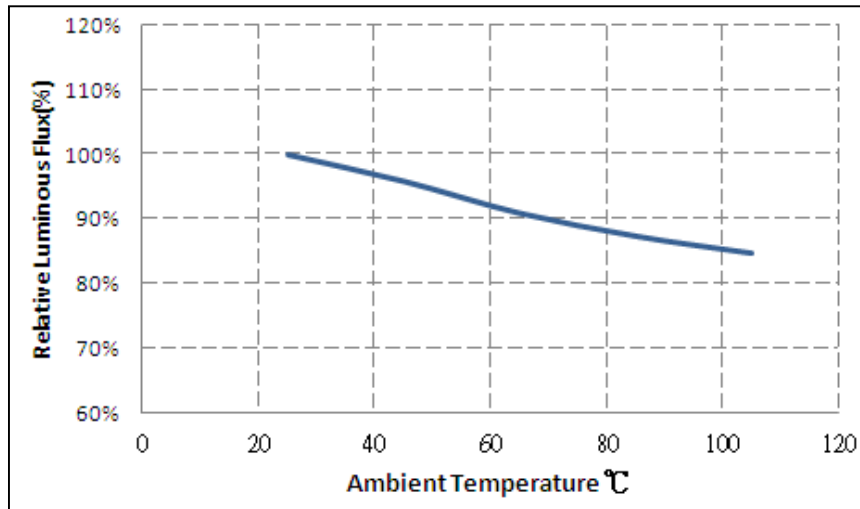
### ■ Chromaticity Coordinate vs. Ambient Temperature



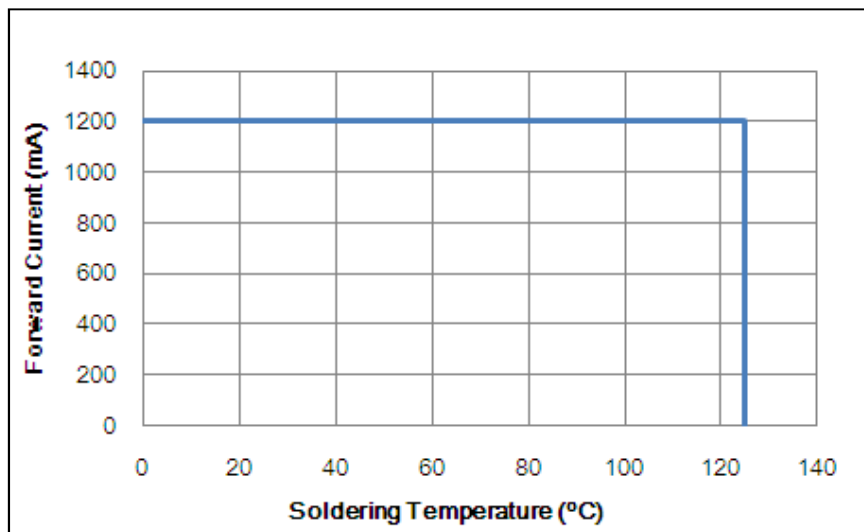
### ■ Relative Forward Voltage vs. Ambient Temperature



### ■ Relative Luminous Intensity vs. Ambient Temperature



### ■ Forward Current Derating Curve



**Reliability**

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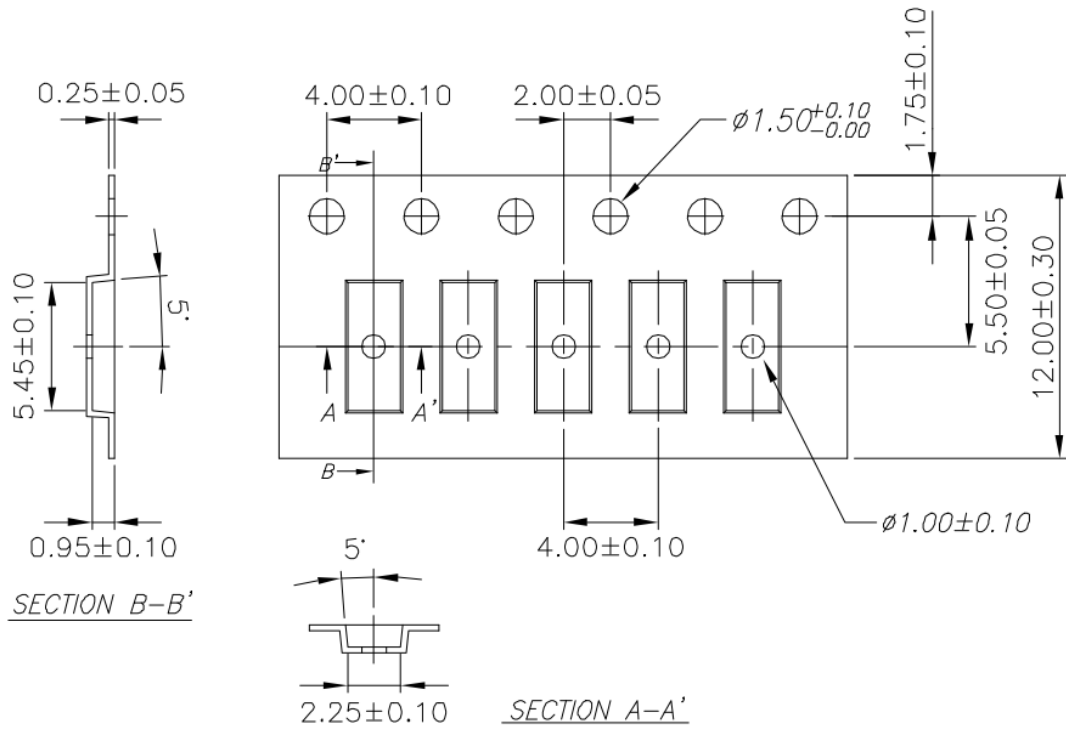
**Reliability test**

Item	Condition	Current	Time/Cycle
High Temperature Operation Life Test	Ts=100°C	1200mA	1000 Hrs
Low Temperature Operation Life Test	Ta=-40°C	1200mA	1000 Hrs
High Temperature and High Humidity Operation Life Test	Ts=85°C , 85%RH	1200mA	1000 Hrs
High Temperature Storage	Ta=100°C	NA	1000 Hrs
Low Temperature Storage	Ta=-40°C	NA	1000 Hrs
High Temperature High Humidity Storage	Ta=85°C , 85%RH	NA	1000 Hrs
Thermal shock	-40°C/20minr ~5minr ~ 125°C/20min	NA	100 Cycles

**Judgment Criteria**

Item	Symbol	Test Condition	Judgment Criteria
Forward Voltage	Vf	1200 mA	$\Delta V_f < 10 \%$
Luminous Flux	Iv	1200 mA	$\Delta I_v < 20 \%$

■ Emitter Pocket Tape Packing



Unit : mm

Item	Spec	Tol(+/-)	Item	Spec	Tol(+/-)
W	12.00	±0.30	P2	2.00	±0.05
E	1.75	±0.10	P0 x 10	40.00	±0.10
F	5.50	±0.05	T	0.25	±0.05
D0	1.50	±0.1	A0	2.25	±0.10
D1	1.50	±0.25	B0	5.45	±0.10
P0 P1	4.00	±0.10	K0	0.95	±0.10

## Packing

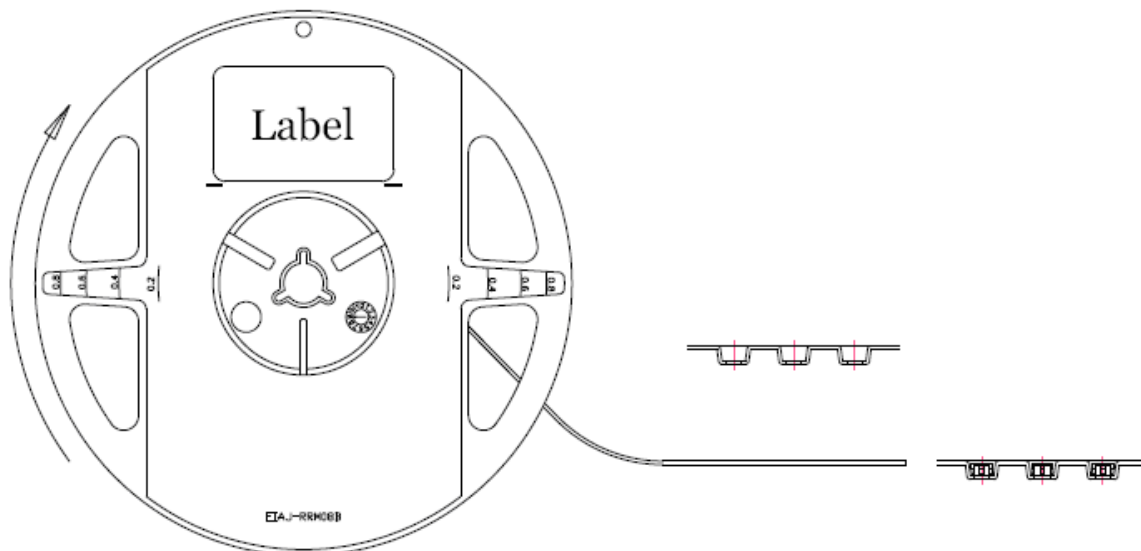
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### Label



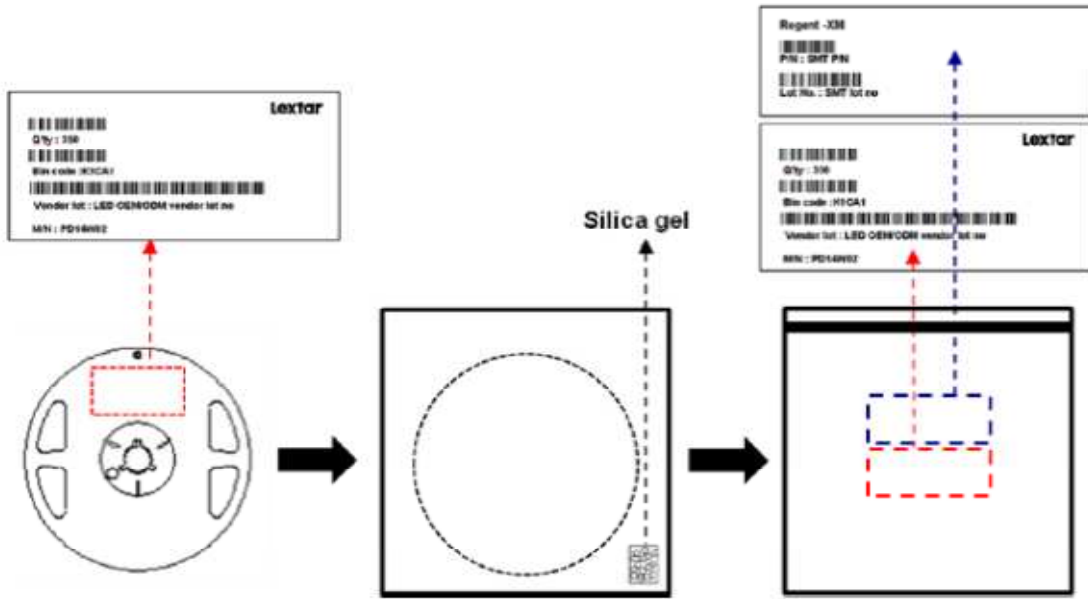
### Carrier Taping



#### Notice:

1. 10 Sprocket hole pitch cumulative tolerance is  $\pm 0.20\text{mm}$ .
2. Carrier camber shall be not more than 1mm per 100mm through a length of 250mm.
3. Ao & Bo measured on a place in the middle of the corner radii.
4. Ko measured from a place on the inside bottom of the pocket to top surface of carrier.
5. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole.
6. Surface resistivity  $10^4 \sim 10^8$  ohm/sq.

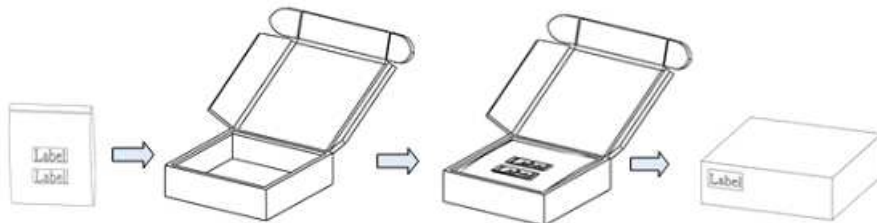
### Shield Bag Taping



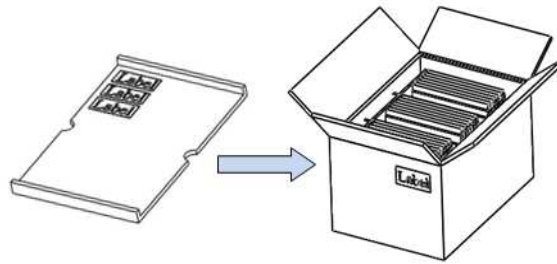
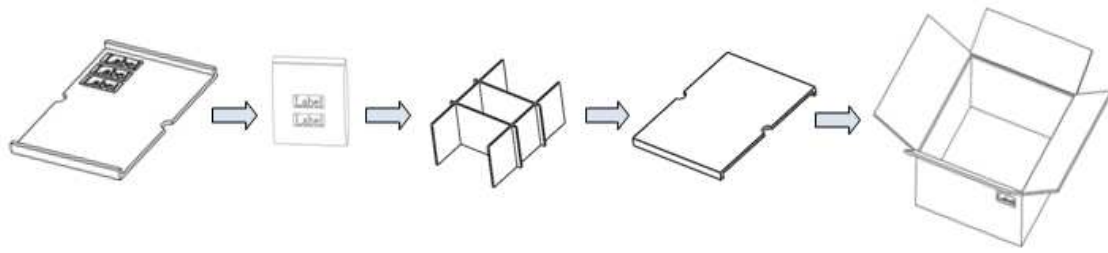
### Packing Box

Type	Large Box		Medium Box		Small Box	
Dimension	541X511X276mm		385X303X260mm		283X235x70mm	
Maximum Reels	7"X12mm Reel	64/R	7"X12mm Reel	21/R	7"X12mm Reel	4/R
Minimum Reels	7"X12mm Reel	32/R	7"X12mm Reel	9/R	7"X12mm Reel	1/R

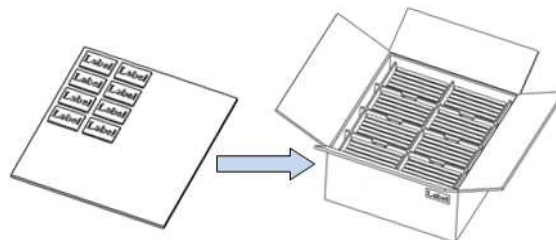
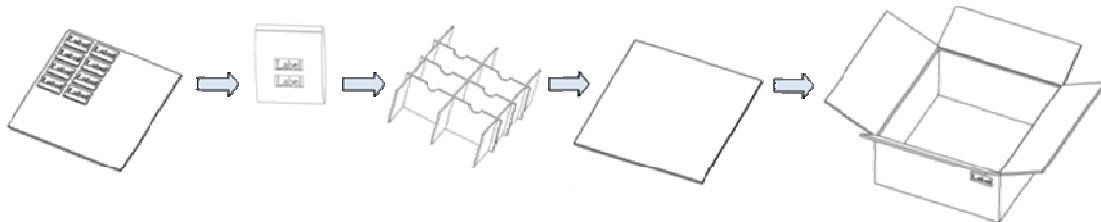
### Small Box



■ **Medium Box**



■ **Large Box**



## Precautions

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### ■ Safety Precautions

- The LED light output is too strong for human eyes without shield. Prevent eye contact directly more than seconds.
- Ensure operating under maximum rating.

### ■ Storage

- Before opening the package, the LEDs should storage under 30°C, 60% RH.
- After opening the package bag, the LEDs should be keep under 30°C, 60% RH. Recommend to use within 168 hrs. If unused LEDs remain, suggest to store into moisture proof bag or original package bag with moisture absorbent material such as silica gel. Reseal well is necessary.
- If the product exceeded the storage period or the moisture absorbent material faded away, baking treatment should be done by following conditions.  
Bake condition: 60°C, 12hours (One time only).

### ■ Soldering Notice and Conditions

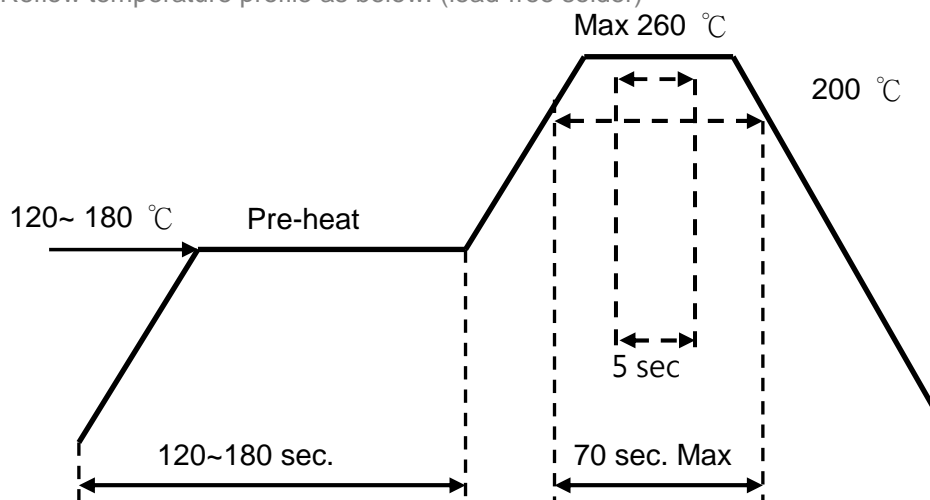
- When soldering LEDs, do not solder/reflow the same LED over two times.
- Recommend soldering conditions:

Hand soldering: 350 °C max, 3 sec. max.

Reflow soldering: Pre-heat 150 °C max, 180 sec. max.

Peak 260 °C max, 5 sec. max.

- Reflow temperature profile as below: (lead-free solder)



- When soldering, don't put stress on the LEDs
- After LEDs have been soldered, strongly recommend not to repair to keep the LEDs performance.



## Revision History

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Date	Contents	Writer	Approved
2017.04.07	Preliminary version	Jackyie Huang	SK Chen
2017.07.17	Renew word description	Jackyie Huang	SK Chen
2017.09.18	Revise flux min bin	Sean Tsai	SK Chen
2017.09.26	Page5: Revise flux bin code definition	SK Chen	Sean Tsai

## *Smart Lighting* *Amazing Life*

Lextar Electronics Corp. is the leading LED (Light Emitting Diode) maker integrating upper stream epitaxial, middle stream chip, and downstream package, SMT and LED lighting applications. Founded in May 2008, Lextar is a subsidiary of AU Optonics, the leading TFT-LCD and solar PV manufacturer. Lextar's product applications include lighting and LCD backlight. Lextar's manufacturing sites include Hsinchu and Chunan in Taiwan, and Suzhou in China.